



- 1 To prevent damage to microphone, do not board wash, clean, or brush board after reflow. Do not expose to ultrasonic processing or cleaning. Do not apply > 30psi to port hole.
- 2 Pin 1 of LS1 is the red wire coming out of the buzzer.

H1 SJ-5303 (CLEAR) H2 SJ-5303 (CLEAR) H3 SJ-5303 (CLEAR) H4 SJ-5303 (CLEAR)

DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-01236
PCB Rev: E1

PCB LOGO Pb-Free Symbol PCB LOGO FCC disclaimer

| Variant/Label Table | |
|---------------------|-------------|
| Variant | Label Text |
| 001 | TBD: TIDA # |
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LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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